



DT2041-04SO

### **Product Summary**

| VBR | (Min) | IPP (Max) | Ст (Тур) |
|-----|-------|-----------|----------|
| 6   | V     | 10A       | 1.0pF    |

### Description

The DT2041-04SO is a high-performance device suitable for protecting four high speed I/Os. These devices are assembled in SOT26 package and have high ESD surge capability and low capacitance.

## **Applications**

Typically used at high-speed ports such as USB 2.0, IEEE1394 (Firewire®, iLink), Serial ATA, DVI™, HDMI™, PCI.

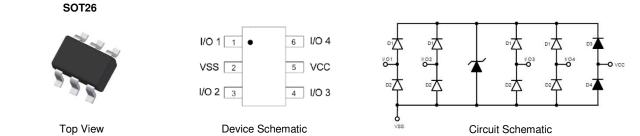
### 4 CHANNEL LOW CAPACITANCE TVS DIODE ARRAY

### Features

- Low Clamping Voltage: Typical 9V at 10A 100ns, TLP, I/O to V<sub>SS</sub>; Typical 8V at 10A 100ns, TLP, V<sub>CC</sub> to V<sub>SS</sub>
- IEC 61000-4-2 (ESD): Air ±30kV, Contact ±30kV
- IEC61000-4-5(Lighting):10A,I/O to  $V_{SS}$ ; 12A,  $V_{CC}$  to  $V_{SS}$
- TLP Dynamic Resistance: 0.25Ω
- Low Channel Input Capacitance of 1.0pF Typical
- 4 Channel of ESD Protection
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

## **Mechanical Data**

- Case: SOT26
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish Annealed over Copper Leadframe (Lead Free Plating) Solderable per MIL-STD-202, Method208 (3)
- Weight: 0.016 grams (Approximate)



### Ordering Information (Note 4)

| Product       | Compliance | Marking | Reel Size (inches) | Tape Width (mm) | Quantity per Reel |
|---------------|------------|---------|--------------------|-----------------|-------------------|
| DT2041-04SO-7 | Standard   | BC4     | 7                  | 8               | 3,000/Tape & Reel |

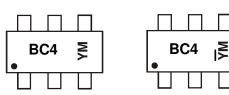
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.

2. See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

# **Marking Information**



BC4 = Product Type Marking Code YM = Date Code Marking Y = Year (ex: D = 2016) M = Month (ex: 9 = September) Note: "—" Represents Internal Code

Date Code Key

Notes:

| Year  | 20  | 16  | 20  | 17  | 20  | 18  | 20  | 19  | 20  | 20  | 20  | 21  |
|-------|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|
| Code  | Γ   | )   | E   |     | F   |     | (   | G   | ŀ   | 4   |     |     |
| Month | Jan | Feb | Mar | Apr | May | Jun | Jul | Aug | Sep | Oct | Nov | Dec |
| Code  | 1   | 2   | 3   | 4   | 5   | 6   | 7   | 8   | 9   | 0   | Ν   | D   |



# **Maximum Ratings** (@ $T_A = +25^{\circ}C$ , unless otherwise specified.)

| Characteristic                                       | Symbol           | Value       | Unit | Conditions                                   |
|--|------------------|-------------|------|--|
| Peak Pulse Current, per IEC61000-4-5                 | IPP              | ±10         | A    | I/O to V <sub>SS</sub> , 8/20 μs             |
| Peak Pulse Current, per IEC61000-4-5                 | IPP              | ±12         | A    | V <sub>CC</sub> to V <sub>SS</sub> , 8/20 µs |
| Peak Pulse Power, per IEC61000-4-5                   | P <sub>PP</sub>  | 105         | W    | I/O to V <sub>SS</sub> , 8/20 μs             |
| Operating Voltage (DC)                               | V <sub>DC</sub>  | 5.5         | V    | I/O to $V_{SS}$ , $V_{CC}$ to $V_{SS}$       |
| ESD Protection – Contact Discharge, per IEC61000-4-2 | VESD_CONTACT     | ±30         | kV   | I/O to $V_{SS}$ , $V_{CC}$ to $V_{SS}$       |
| ESD Protection – Air Discharge, per IEC61000-4-2     | Vesd_air         | ±30         | kV   | I/O to $V_{SS}$ , $V_{CC}$ to $V_{SS}$       |
| Operating Temperature                                | T <sub>OP</sub>  | -55 to +85  | °C   |  |
| Storage Temperature                                  | T <sub>STG</sub> | -55 to +150 | °C   |  |

## Thermal Characteristics

| Characteristic   | Symbol           | Value | Unit |
|--|------------------|-------|------|
| Power Dissipation Typical (Note 5)                       | PD               | 300   | mW   |
| Thermal Resistance, Junction to Ambient Typical (Note 5) | R <sub>θJA</sub> | 417   | °C/W |

# Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

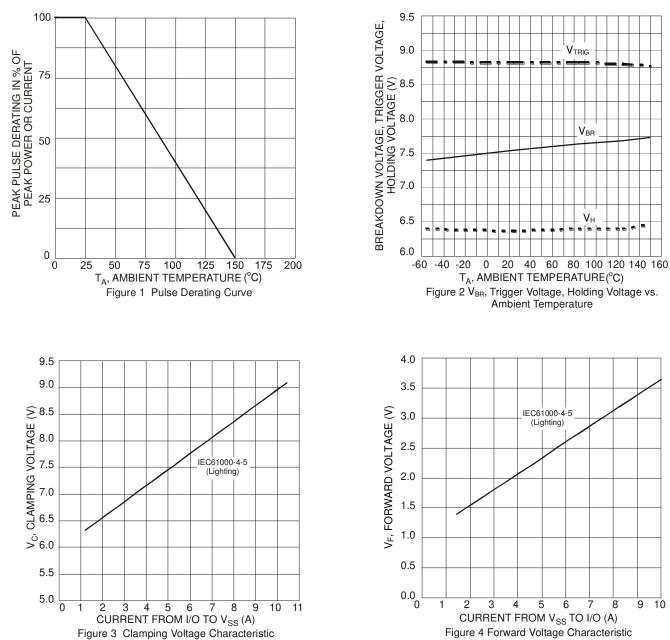
| Characteristic                         | Symbol             | Min  | Тур  | Max  | Unit | Test Conditions   |
|--|--------------------|------|------|------|------|---|
| Reverse Working Voltage                | V <sub>RWM</sub>   |      |      | 5.5  | V    | I/O to V <sub>SS</sub> , V <sub>CC</sub> to V <sub>SS</sub>   |
| Reverse Current (Note 6)               | I <sub>R</sub>     |      |      | 1    | μA   | $V_R = 5V$ , I/O to $V_{SS}$ , $V_{CC}$ to $V_{SS}$   |
| Reverse Breakdown Voltage              | V <sub>BR</sub>    | 6    |      | 9    | V    | $I_R = 1mA$ , I/O to $V_{SS}$ , $V_{CC}$ to $V_{SS}$  |
| Forward Clamping Voltage               | VF                 | -1.0 | -0.8 |      | V    | $I_{\text{F}}$ = -15mA, I/O to $V_{\text{SS}}, V_{\text{CC}}$ to $V_{\text{SS}}$  |
| Holding Voltage                        | V <sub>H</sub>     | 5.5  |      |      | V    | —   |
| Trigger Voltage                        | V <sub>TRIG</sub>  |      | 9    | 9.5  | V    | —   |
| Reverse Clamping Voltage (Note 7)      | Vc_5a              |      | 7.5  |      | V    | $I_{PP} = 5A$ , I/O to V <sub>SS</sub> , 8/20 µs  |
| Reverse Clamping Voltage (Note 7)      | V <sub>C_10A</sub> |      | 9    | 10.5 | V    | $I_{PP} = 10A$ , I/O to V <sub>SS</sub> , 8/20 µs   |
| ESD Clamping Voltage                   | V <sub>ESD</sub>   |      | 9    |      | v    | TLP, 10A, tp = 100ns, I/O to V <sub>SS</sub>  |
| ESD Clamping Voltage                   |                    |      | 8    |      | v    | TLP, 10A, tp = 100ns, $V_{CC}$ to $V_{SS}$  |
| Dynamic Resistance                     | R <sub>DIF</sub>   |      | 0.25 |      | Ω    | TLP, 10A, tp = 100ns, I/O to $V_{SS}$   |
|  |                    |      | 0.15 |      | 12   | TLP, 10A, tp = 100ns, $V_{CC}$ to $V_{SS}$  |
| Channel Input Capacitance              | CT                 |      | 1.0  | 1.5  | pF   | $V_{I/O} = 2.5V, V_{CC}=5V, f = 1MHz$   |
| Variation of Channel Input Capacitance | $\Delta C_T$       |      | 0.02 |      | pF   | $\label{eq:VSS} \begin{array}{l} V_{SS} = 0V, \ V_{I/O} = 2.5V, \ f = 1MHz, \\ I/O_x \text{ to } V_{SS} - I/O_y \text{ to } V_{SS} \end{array}$ |

Notes: 5. Device mounted on FR-4 PCB pad layout (2oz copper) as shown on Diodes, Inc. suggested pad layout, which can be found on our website at http://www.diodes.com/package-outlines.html.

6. Short duration pulse test used to minimize self-heating effect.

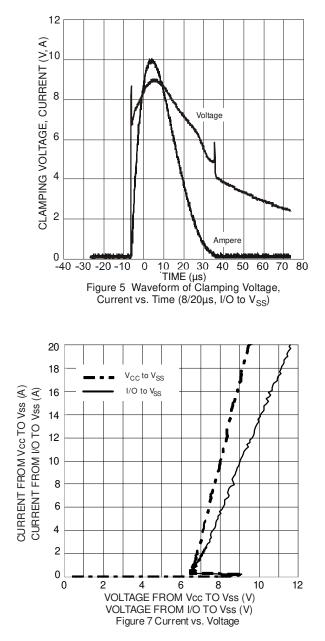
7. Clamping voltage value is based on an  $8x20\mu s$  peak pulse current (Ipp) waveform.

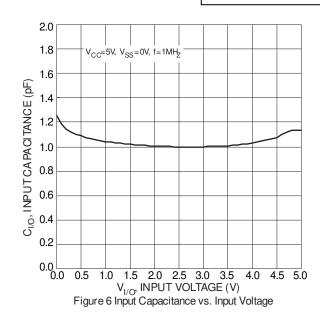




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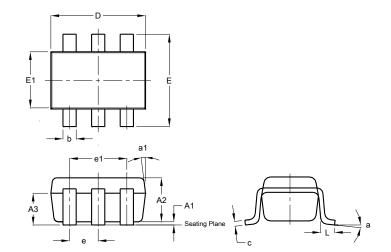






# **Package Outline Dimensions**

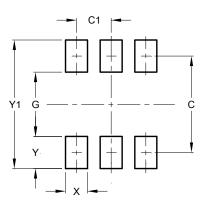
Please see http://www.diodes.com/package-outlines.html for the latest version.



|     | SC    | DT26  |       |
|-----|-------|-------|-------|
| Dim | Min   | Max   | Тур   |
| A1  | 0.013 | 0.10  | 0.05  |
| A2  | 1.00  | 1.30  | 1.10  |
| A3  | 0.70  | 0.80  | 0.75  |
| b   | 0.35  | 0.50  | 0.38  |
| С   | 0.10  | 0.20  | 0.15  |
| D   | 2.90  | 3.10  | 3.00  |
| е   | -     | -     | 0.95  |
| e1  | -     | -     | 1.90  |
| ш   | 2.70  | 3.00  | 2.80  |
| E1  | 1.50  | 1.70  | 1.60  |
| L   | 0.35  | 0.55  | 0.40  |
| а   | -     | -     | 8°    |
| a1  | -     | -     | 7°    |
| All | Dimen | sions | in mm |

# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.



SOT26

SOT26

| Dimensions | Value (in mm) |
|------------|---------------|
| С          | 2.40          |
| C1         | 0.95          |
| G          | 1.60          |
| Х          | 0.55          |
| Y          | 0.80          |
| Y1         | 3.20          |



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